

# Symposium on Materials in Advanced Packaging

ASME International Mechanical Engineering Congress and R&D Expo

Seattle, Washington, USA

November 10-16, 2007

<https://www.asmeconferences.org/Congress07/index.cfm>

**Abstract submission deadline: March 5, 2007**

Novel packaging materials would offer innovative and disruptive solutions to the challenges in electronics, MEMS, photonics and organic electronics. Further, in order to keep up with the most advanced concepts, a better understanding of materials and their microstructural developments is essential. This symposium focuses on materials issues encountered in the assembly and packaging. Additionally, materials issues on low-k dielectrics will be included in this symposium due to its interface and interaction with the flip-chip and wire-bond packaging. **Topics of special interests** in this symposium include, but are not limited to: Materials issues in low-k dielectrics; Materials design and development in electronic, MEMS, and photonic packaging; Barrier coatings and flexible substrates for OLED; Thin films, coatings and adhesives in packaging, Interfacial phenomena and microstructure-property relationships of packaging materials; Integration of passive components and smart materials into packaging; Processing and measurement issues (thermal, mechanical, and electrical); Nanoscale phenomena and its relation to packaging reliability; Combined approaches through modeling and experimental work.

This symposium consists of the following 4 sessions:

- Low-k dielectric materials
- Materials issues for organic electronics
- Structure-property relations (physical, mechanical, electrical, thermal)
- Nanostructured/nanoscale materials in packaging

To submit an abstract, please follow the abstract submission guidelines posted on the IMECE2007 conference website and select the **Track 9 Electronics and Photonics** and **9-14 Symposium on Materials in Advanced Packaging**.

If you have any questions, please contact:

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